查询BYW51-200G供应商

专业PCB打样工厂,24小时加急出货

BYW51-200

SWITCHMODE[™] **Power Rectifier**

Features and Benefits

- Low Forward Voltage
- Low Power Loss/High Efficiency
- High Surge Capacity
- 175°C Operating Junction Temperature
- 16 A Total (8 A Per Diode Leg)
- Pb-Free Packages are Available*

Applications

- Power Supply Output Rectification
- Power Management
- Instrumentation

Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Rating: Human Body Model 3B Machine Model C



ON Semiconductor®

http://onsemi.com

ULTRAFAST RECTIFIER 16 AMPERES, 200 VOLTS

t_{rr} = 35 ns

MARKING DIAGRAM



AYWW BYW51-200G AKA

A	= Assembly Location
Y	= Year
WW	= Work Week
BYW51–200	= Device Code
G	= Pb-Free Package
AKA	= Diode Polarity
G	= Device Code = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
BYW51-200	TO-220	50 Units/Rail
BYW51-200G	TO-220 (Pb-Free)	50 Units/Rail

dzsc.com

For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques eference Manual, SOLDERRM/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current $T_{C} = 156^{\circ}C$ Per Leg Total Device	I _{F(AV)}	8.0 16	A
Peak Rectified Forward Current (Square Wave, 20 kHz), $T_{C} = 153^{\circ}C - Per Diode Leg$	I _{FM}	16	A
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	100	A
Operating Junction Temperature and Storage Temperature	T _J , T _{stg}	-65 to +175	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

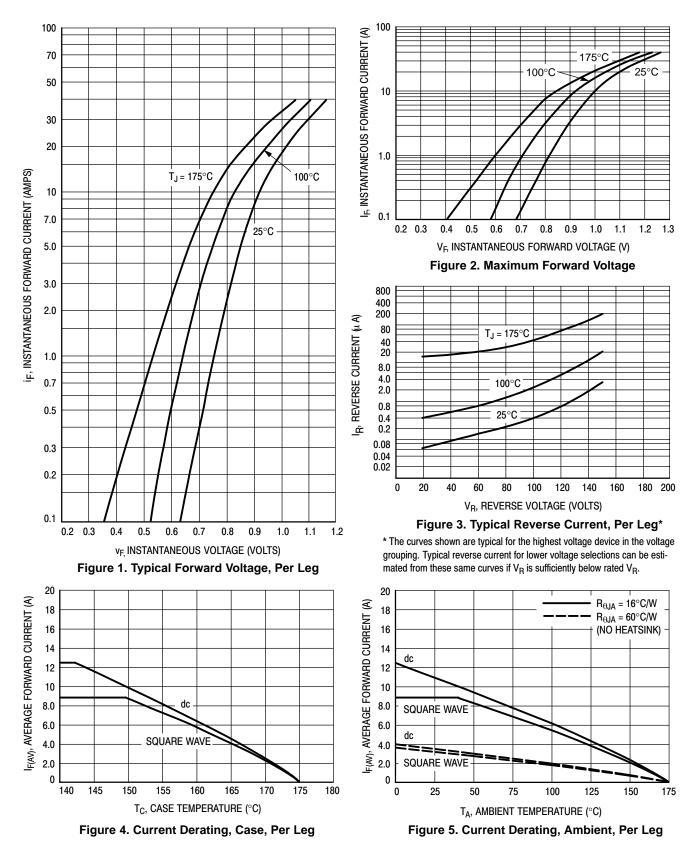
THERMAL CHARACTERISTICS

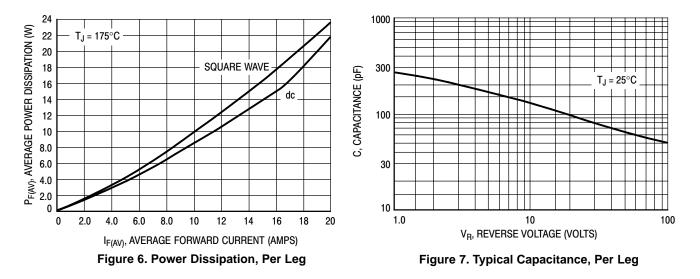
Characteristic	Conditions	Symbol	Value	Unit
Maximum Thermal Resistance, Junction-to-Case	Min. Pad	$R_{\theta JC}$	3.0	°C/W
Maximum Thermal Resistance, Junction-to-Ambient	Min. Pad	$R_{\theta JA}$	60.0	

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min	Typical	Max	Unit
Instantaneous Forward Voltage (Note 1) (i _F = 8.0 A, T _j = 100°C) (i _F = 8.0 A, T _j = 25°C)	VF		0.8 0.89	0.89 0.97	V
Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_j = 100^{\circ}C$) (Rated dc Voltage, $T_j = 25^{\circ}C$)	i _R		21 3.8	1000 10	μΑ
Maximum Reverse Recovery Time ($I_F = 1.0 \text{ A}$, di/dt = 50 A/s) ($I_F = 0.5 \text{ A}$, $I_R = 1.0 \text{ A}$, $I_{REC} = 0.25 \text{ A}$)	t _{rr}	_	-	35 25	ns

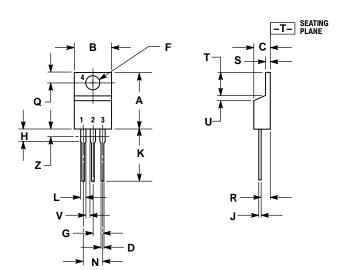
1. Pulse Test: Pulse Width = 300 s, Duty Cycle $\leq 2.0\%$





PACKAGE DIMENSIONS

TO-220 CASE 221A-09 ISSUE AD



NOTES:

 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 CONTROLLING DIMENSION: INCH.
DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
Ν	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
۷	0.045		1.15	
Ζ		0.080		2.04

STYLE 6: PIN 1. ANODE

2. CATHODE

3. ANODE

4. CATHODE

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